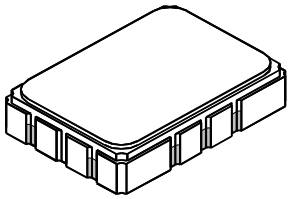
Preliminary

SF1102B

230 MHz SAW Filter

- ***Designed for WCDMA 3G IF Applications***
- ***Quartz Temperature Stability***
- ***Small Size***
- ***Hermetic 7 x 5 Surface-Mount Case***
- ***Complies with Directive 2002/95/EC (RoHS)***



SMP-03

Absolute Maximum Ratings

Rating	Value	Units
Maximum Incident Power in Passband	+10	dBm
Max. DC voltage between any 2 terminals	30	VDC
Storage Temperature Range	-40 to +85	°C
Suitable for lead-free soldering - Max. Soldering Profile	260°C for 30 s	

Electrical Characteristics

Characteristic		Sym	Notes	Min	Typ	Max	Units
Nominal Center Frequency		f_C	1		230.000		MHz
Passband	Insertion Loss at fc	IL			16	18.0	dB
	1 dB Passband	BW_1	1, 2	±2.0	±2.2		MHz
	3 dB Passband	BW_3			±2.5		
	Amplitude Ripple over fc±2.0 MHz					1.0	dB_{P-P}
	Group Delay Variation over fc±2.0 MHz	GDV			100	150	ns_{P-P}
Rejection	fc-25 to fc-5.0		1, 2, 3	40			dB
	fc+5 to fc+25			38			
Operating Temperature Range		T_A	1	-20		+80	°C

Matching to Unbalanced 50 Ω		External L-C
Case Style	6	SMP-03 7 x 5 mm Nominal Footprint
Lid Symbolization (YY = year, WW = week)		RFM SF1102B YYWW

Notes:

1. Unless noted otherwise, all specifications apply over the operating temperature range with filter soldered to the specified demonstration board with impedance matching to 50 Ω and measured with 50 Ω network analyzer.
2. Unless noted otherwise, all frequency specifications are referenced to the nominal center frequency, fc.
3. Rejection is measured as attenuation below the minimum IL point in the passband. Rejection in final user application is dependent on PCB layout and external impedance matching design. See Application Note No. 42 for details.
4. "LRIP" or "L" after the part number indicates "low rate initial production" and "ENG" or "E" indicates "engineering prototypes."
5. The design, manufacturing process, and specifications of this filter are subject to change.
6. Tape and Reel Standard ANSI / EIA 481.
7. Either Port 1 or Port 2 may be used for either input or output in the design. However, impedances and impedance matching may vary between Port 1 and Port 2, so that the filter must always be installed in one direction per the circuit design.
8. US and international patents may apply.
9. Electrostatic Sensitive Device. Observe precautions for handling.

Electrical Connections

Connection	Terminals
Port 1 Hot	10
Port 1 Gnd Return	1
Port 2 Hot	5
Port 2 Gnd Return	6
Case Ground	All others

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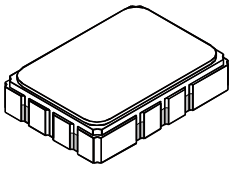
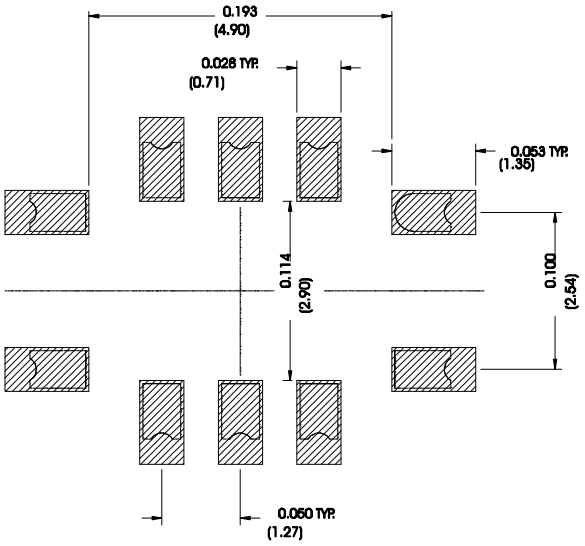
SMP-03 Case

10-Terminal Ceramic Surface-Mount Case
7 x 5 mm Nominal Footprint



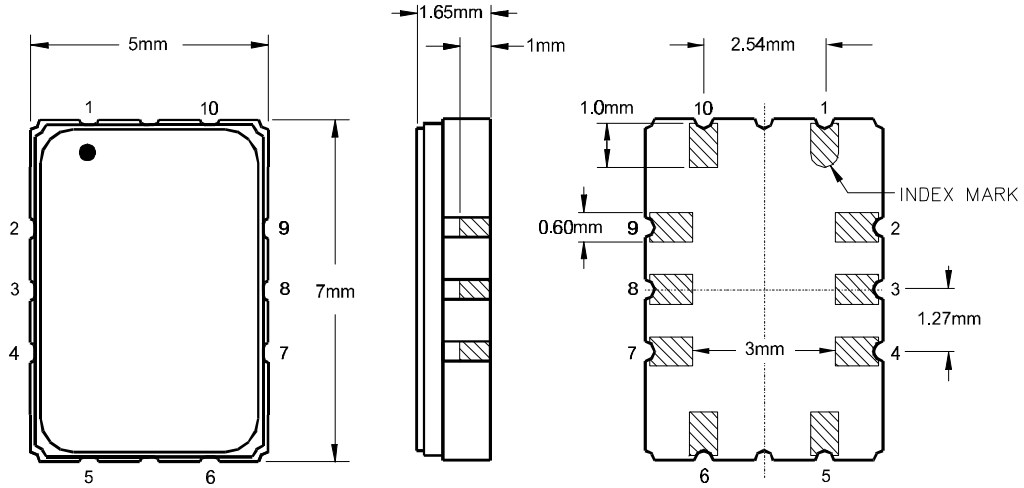
Recommended PCB Footprint



Case Dimensions						
Dimension	**mm**			**Inches**		
	Min	**Nom**	**Max**	**Min**	**Nom**	**Max**
A	6.80	7.00	7.20	0.268	0.276	0.283
B	4.80	5.00	5.20	0.189	0.197	0.205
C		1.65	2.00		0.065	0.079
D		0.60			0.024	
E		2.54			0.100	
H		1.0			0.039	
J		5.00			0.197	
K		3.00			0.118	
P		1.27			0.050	

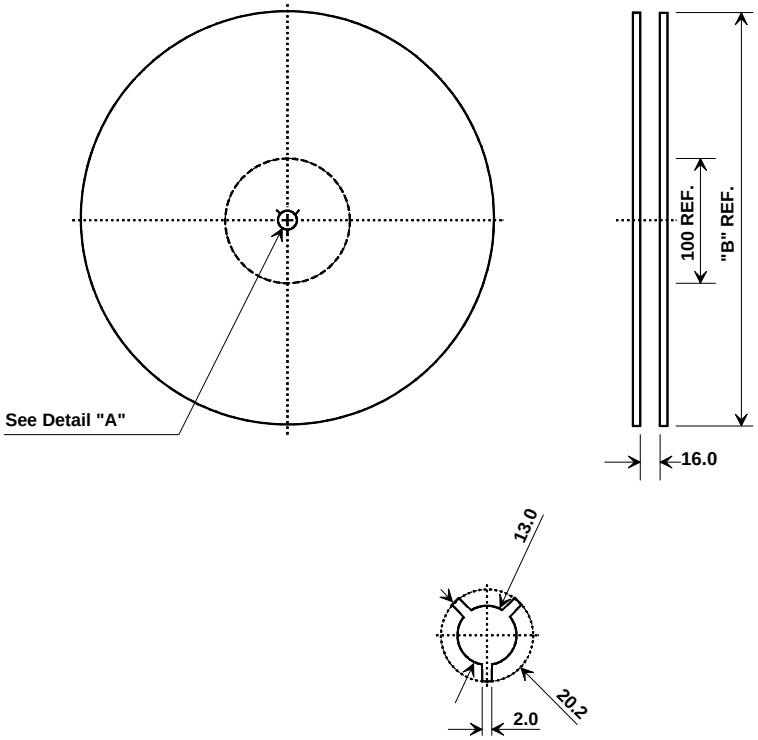
Electrical Connections		
Connection		**Terminals**
Port 1	Input or Return	10
	Return or Input	1
Port 2	Output or Return	5
	Return or Output	6
Ground		All others
Single Ended Operation		**Return is ground**
Differential Operation		**Return is hot**

Materials	
Solder Pad Termination	Au plating 30 - 60 uInches (76.2-152 uM) over 80-200 uInches (203-508 uM) Ni.
Lid	Fe-Ni-Co Alloy Electroless Nickel Plate (8-11% Phosphorus) 100-200 uInches Thick
Body	Al_2O_3 Ceramic
Pb Free	



TOP VIEW BOTTOM VIEW

Tape and Reel Specifications



"B " Nominal Size		Quantity Per Reel
Inches	millimeters	
7	178	500
13	330	2000

COMPONENT ORIENTATION and DIMENSIONS

Carrier Tape Dimensions	
Ao	5.5 mm
Bo	7.5 mm
Ko	2.0 mm
Pitch	8.0 mm
W	16.0 mm